

<b>Examiner-Initiated Interview Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/772,541	AGARWAL ET AL.	
	<b>Examiner</b>	<b>Art Unit</b>	
	Yewebdar T. Tadesse	1734	

**All Participants:**
**Status of Application:** After Final

 (1) Yewebdar T. Tadesse.

(3) \_\_\_\_\_.

 (2) Chen Liang.

(4) \_\_\_\_\_.

**Date of Interview:** 8 March 2006
**Time:** \_\_\_\_

**Type of Interview:**

- ☒ Telephonic  
☐ Video Conference  
☐ Personal (Copy given to: ☐ Applicant ☐ Applicant's representative)

**Exhibit Shown or Demonstrated:** ☐ Yes ☐ No

If Yes, provide a brief description: \_\_\_\_\_

**Part I.**
**Rejection(s) discussed:**

None

**Claims discussed:**

68, 69, 72, 75, 78 and 79

**Prior art documents discussed:**

None

**Part II.**
**SUBSTANCE OF INTERVIEW DESCRIBING THE GENERAL NATURE OF WHAT WAS DISCUSSED:**
*examiner requested the attorney to clearly define the claimed invention (see enclosed attorney's proposals and Examiner's amendment)*
**Part III.**

- ☐ It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview directly resulted in the allowance of the application. The examiner will provide a written summary of the substance of the interview in the Notice of Allowability.  
☐ It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview did not result in resolution of all issues. A brief summary by the examiner appears in Part II above.

  
 (Examiner/SPE Signature)

\_\_\_\_\_  
 (Applicant/Applicant's Representative Signature – if appropriate)

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Examiner Tadesse	USPTO	571-272-1238	571-273-1238

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[FAXCOVER.01]

Attorney Docket No. 10829-8404US2

## PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: VISHNU K. AGARWAL AND  
DINESH CHOPRA

APPLICATION No.: 10/772,541

FILED: FEBRUARY 5, 2004

FOR: APPARATUSES FOR FORMING A  
PLANARIZING PAD FOR  
PLANARIZATION OF  
MICROELECTRONIC SUBSTRATES

EXAMINER: YEWEDAR T.  
TADESSE

ART UNIT: 1734

CONF. No: 8900

**Proposed Claim Amendment -**

**For Discussion Purposes Only**

**Amendment to the Claims:**

67. (Canceled).

68. (Previously Presented) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel configured to contain a non-solid planarizing pad material;

at least one nozzle positioned over the support device and operatively coupled to the vessel and coupled to a source of compressed gas, the nozzle being configured to mix the planarizing pad material with the compressed gas to form discrete texture elements for disposing on the support material; and

a hopper positioned between the nozzle and the support device, the hopper having a first opening proximate to the at least one nozzle for

receiving the discrete texture elements and a second opening proximate to the support material for disposing the received discrete texture elements on the support material when the support material is supported by the support device.

69. (Previously Presented) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel configured to contain a non-solid planarizing pad material; and

at least one nozzle positioned over the support device and operatively coupled to the vessel and coupled to a source of compressed gas, the nozzle being configured to mix the planarizing pad material with the compressed gas to form discrete texture elements for disposing on the support material;

wherein the support material is elongated in a longitudinal direction and the at least one nozzle is the first of two nozzles coupled to the vessel, the second nozzle being offset in the longitudinal direction and in a lateral direction transverse to the longitudinal direction relative to the first nozzle.

70. (Original) The apparatus of claim 69, further comprising:

a manifold coupled to the vessel;

a first spraybar coupled to the manifold and extending over the support material in transverse direction when the support material is supported by the support device, the first nozzle being connected to the first spraybar; and

a second spraybar coupled to the manifold and spaced apart from the first spraybar in the longitudinal direction, the second spraybar extending transversely over the support material when the support material is supported by the support device, the second nozzle being connected to the second spraybar.

71. (Previously Presented) The apparatus of claim 69, further comprising a heating element positioned proximate to the support device and proximate to the pad support material when the pad support material is supported by the support device.

72. (Previously Presented) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel configured to contain a non-solid planarizing pad material;

at least one nozzle positioned over the support device and operatively coupled to the vessel and coupled to a source of compressed gas, the nozzle being configured to mix the planarizing pad material with the compressed gas to form discrete texture elements for disposing on the support material; and  
a grate between the nozzle and the support device, the grate having a plurality of apertures sized to pass the discrete texture elements therethrough.

73. (Previously Presented) The apparatus of claim 69 wherein the first and second nozzles are positioned to spray the discrete texture elements directly onto the support material.

74. (Previously Presented) The apparatus of claim 68 wherein the vessel is a first vessel, and wherein the apparatus further comprises a second vessel positioned proximate to the second opening, the second vessel configured to contain the discrete texture elements and a film material.

75. (Currently Amended) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, the apparatus comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel for mixing a planarizing pad material;

a nozzle in fluid communication with the vessel and configured to form the planarizing pad material into discrete texture elements for disposing on the pad support material, wherein the pad support material is elongated in a longitudinal direction, and wherein the nozzle is positioned over the support device to spray the discrete texture elements at least partially in the longitudinal direction; and

a hopper positioned between the nozzle and the support device, the hopper having a first opening positioned proximate to the nozzle for receiving the discrete texture elements and a second opening proximate to the support material for disposing the received discrete texture elements on the support material when the support material is supported by the support device.

76. (Canceled).

77. (Canceled).

78. (Currently Amended) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, the apparatus comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel for mixing a planarizing pad material; and  
a nozzle in fluid communication with the vessel and configured to form the planarizing pad material into discrete texture elements for disposing on the support material, wherein the pad support material is elongated in a longitudinal direction, and wherein the nozzle is positioned over the support device to spray the discrete texture elements at least partially in the longitudinal direction, wherein the support material is elongated in a longitudinal direction and the nozzle is a first nozzle, and wherein the apparatus further comprises a second nozzle in fluid communication with the vessel, the second nozzle being positioned over the support device and offset in the longitudinal direction and in a lateral direction transverse to the longitudinal direction relative to the first nozzle.

79. (Previously Presented) An apparatus for forming a planarizing pad for mechanically and/or chemically-mechanically planarizing a microelectronic substrate, the apparatus comprising:

a support device configured to support a pad support material in a selected position, wherein the support device includes first and second rollers coupled to the support material and rotatable relative to each other to advance the support material from the first roller to the second roller;

a vessel for mixing a planarizing pad material;

a nozzle in fluid communication with the vessel and configured to form the planarizing pad material into discrete texture elements for disposing on the support material, wherein the pad support material is elongated in a longitudinal direction, and wherein the nozzle is positioned over the support device to spray the discrete texture elements at least partially in the longitudinal direction;

a manifold coupled to the vessel;

a first spraybar coupled to the manifold and extending over the support material in transverse direction when the support material is supported by the support device, the first nozzle being connected to the first spraybar; and

a second spraybar coupled to the manifold and spaced apart from the first spraybar in the longitudinal direction, the second spraybar extending transversely over the support material when the support material is supported by the support device, the second nozzle being connected to the second spraybar.

80. (Previously Presented) The apparatus of claim 75, further comprising a heating element positioned proximate to the support device and proximate to the pad support material when the pad support material is supported by the support device.

81. (Previously Presented) The apparatus of claim 75, further comprising a grate between the nozzle and the support device, the grate having a plurality of apertures sized to pass the discrete texture elements therethrough.

82. (Canceled).

83. (Previously Presented) The apparatus of claim 75 wherein the vessel is a first vessel, and wherein the apparatus further comprises:

a second vessel positioned proximate to the second opening, the second vessel configured to contain the discrete texture elements and a film material.



**Remarks**

The foregoing claim amendments are provided for discussion purposes only in a telephone interview scheduled for \_\_\_\_\_ p.m. Eastern time between the Examiner and the attorney identified below.

Respectfully submitted,  
Perkins Coie LLP

Date: \_\_\_\_\_

\_\_\_\_\_  
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